



Design Review Checklist

Schematic Circuit Diagram



- ☐ Ensure that there are no missing net ties and schematic ports across all schematic sheets.
- ☐ Ensure that design rules matching the PCB manufacturer's capabilities have been implemented.
- ☐ Ensure that all component decoupling capacitors be clearly identified, with a proper note about placement close to the supply pins of the processor.
- ☐ Add appropriate notes regarding:
 - a. trace width for high current traces
 - b. trace length matching for high-speed traces with matching propagation delay requirements.
 - c. controlled impedance traces, include the expected impedance of such traces.
 - d. traces carrying low noise signals. Indicate that they are to be separated from high current traces or traces carrying fast signals.
 - e. trace separation clearances for high voltage trace. Indicate if physical barriers such as PCB slots are needed.
- ☐ Properly identify passive components with specific characteristics such as high power or precision resistors, low temperature coefficient, or low ESR capacitors and others
- ☐ Unused pins on IC's should be confirmed to be no net connection, or pulled up or pulled down.
- ☐ Check all schematic capture compilation warnings. Do not ignore any unless there is a good reason for doing so.



- ☐ Ensure the IC outputs such as I2C SDA or SCL have proper pull-up resistors.
- ☐ Ensure that clamp diodes and transient suppressors have been included in all externally exposed connections.
- ☐ If there are different types of Ground, eg. Signal ground or Power ground, make sure to properly label each ground with its type.
- ☐ Identify magnetic components, such as power inductors, that could cross-couple. Make a note about properly spacing, or orienting, them.
- ☐ Identify high heat generating components and temperature sensitive components, and add a note that they are to be properly physically separated.
- ☐ Identify circuit sections that need to be shielded, and indicate the type of shielding, such as cans, needed.
- ☐ Indicate the need of guard rings around very sensitive low-level signal input pins.
- ☐ Do not place high voltage and low voltage lines adjacent to each other on connector pins on the schematic.
- ☐ Use multiple connector pins for carrying high current, taking into account the current carrying capability of each pin of the selected connector.
- ☐ If using PCB heatsink or on-board heatsinks, specify keep-out area.
- ☐ Specify Do-Not-Populate (DNP) components.
- ☐ Add appropriate test points to critical nodes.



- ☐ Specify test point surface treatment, if required.
- ☐ Specify surface treatment, such as gold plating of a given thickness, for edge connector fingers.